

Infineon HP XHP IGBT – SBE DC Link Capacitor – Rogers Rolinx Bus – Dupont Teijin PEN HV Dielectric Film

Infineon FF450R33TE3 - 3.3kV XHPTM3 Half-bridge Module

- 450A 3300V Dual IGBT module
- Flexible and scalable module platform to meet a wide range of applications such as Traction – Propulsion and auxiliary drives, HVDC transmission systems and Medium-voltage drives.
- Module platform also available for 4.5 kV and 6.5 kV voltage class.
- Robust package design to meet application and environmental requirements.

SBE Power Ring Capacitors – 2.4 kV DC Link – 1,000 μ F (250 μ F x 4) – Using patented film design and bus-cap assembly technology.

Rogers Rolinx Bus Bars – Very low ESL – high current laminated bus bars.

Dupont Teijin Films – PEN HV dielectric for high temperature power capacitors – 8 micron – with 140°C+ capability.

Advanced DC Link Capacitor system – This DC Link system presents <10nH ESL to the XHP3 modules allowing complete utilization of the 2.4kV DC Link design with no need for large overshoot margins. Increases to 3.2kV DC Link working voltages are very achievable with appropriate film selection. Available with commonly used MPP film for system ambient temperature limits to 95°C+, this can be expanded to 140°C+ using the Dupont Teijin PEN HV Dielectric film.



SBE



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